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**PATENT ABSTRACTS OF JAPAN**

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(84) Designated contracting states:	(74) Representative:

**(54) METAL PLATING  
DEVICE****(57) Abstract:**

**PURPOSE:** To apply plating at a uniform thickness on the ground surface metal part on the surface to be plated of a semiconductor substrate.

**CONSTITUTION:** This metal plating device is provided with a cup 1 which is covered with a semiconductor substrate 4 on its aperture and stores a plating liquid 6, a bearing 10 which holds a spherical body 9 capable of swiveling a joint part of the cup 1 and a piping 7 for supplying the plating liquid 6, a mechanism which rotates a cathode electrode 5 and cylinders 8a, 8b which lift and down the end of the cup 1. The build-up part of the plating liquid generated by the gushing flow from an ejection port 2 is brought into contact with the substrate by the oscillation of the cup 1 and while the semiconductor substrate 4 is kept rotated, the plating liquid is brought into uniform contact with the overall surface of the surface

to be plated.

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